



## Final Product Change Notification

201803021F01

**Issue Date:** 24-Aug-2018  
**Effective Date:** 21-Nov-2018

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# QUALITY

### Management Summary

MPC8245 and MPC8250/8255/8260/8265 conversion from Glob Top to Center Gate Mold.

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input checked="" type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input type="checkbox"/> Other                         |  |   |   |

MPC8245 and MPC8250/8255/8260/8265 TBGA Product Family Conversion to Center Gate Mold Process

### Description of Change

NXP is pleased to announce a new encapsulation process called Center Gate Mold for the TBGA package variants of the MPC8245 and MPC8250/8255/8260/8265 product families.

Currently, the encapsulation process used on the TBGA package variants of the MPC8245 and MPC8250/8255/8260/8265 product family is the Fine Pitch Glob process. For supply assurance, NXP is adding the Center Gate Mold process to these product families.

Due to the nature of the Center Gate Mold (injection mold) process, the current Dexter FP4451 Dam and Nagase T693/R1001 Glob Filter epoxy will be replaced by the Sumitomo G770SFL Ultra Low Alpha Mold Compound used in established Center Gate Mold products.

## Reason for Change

As part of NXP's continuous improvement efforts, this change is being made to support customer supply assurance.

## Identification of Affected Products

Product identification does not change

## Product Availability

### Sample Information

Samples availability differs by product - see attached sample plan  
See attached sample plan.

### Production

Planned first shipment 21-Nov-2018

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.  
No impact to Form, Fit, Function or Reliability.

Case outline spec is maintained while providing a more dimensionally uniform product. This will be observed as a flatter surface with uniform color.

### Data Sheet Revision

No impact to existing datasheet

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 23-Sep-2018.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Michael Wilson  
**Position** Product Marketer  
**e-mail address** mike.wilson@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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NXP Semiconductors  
High Tech Campus, 5656 AG Eindhoven, The Netherlands



Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Name	Status	Product Line	Notes
MPC8260ACZUMHBB	935316826557	MPC8260ACZUMHBB	POWERQUICC II HIP4 REV B	LBGA480	RFS	BL Digital Networking	MPC8260ACZUMHBB
MPC8265ACZUMIBC	935325352557	MPC8265ACZUMIBC	POWER QUICC II HIP4C	LBGA480	RFS	BL Digital Networking	MPC8265ACZUMIBC
MPC8250ACZUMHBC	935325281557	MPC8250ACZUMHBC	POWER QUICC II HIP4C	LBGA480	RFS	BL Digital Networking	MPC8250ACZUMHBC
MPC8245LVV350D	935321131557	MPC8245LVV350D	INTEGRATED HOST PROC	LBGA352	RFS	BL Digital Networking	MPC8245LVV350D
MPC8245TVV266D	935316715557	MPC8245TVV266D	INTEGRATED HOST PROC	LBGA352	RFS	BL Digital Networking	MPC8245TVV266D